	SN74BCT29864B 9-BIT BUS TRANSCEIVER WITH 3-STATE OUTPUTS SCBS010A – NOVEMBER 1988 – REVISED NOVEMBER 1993
<ul> <li>BiCMOS Design Substantially Reduces Standby Current</li> </ul>	DW OR NT PACKAGE (TOP VIEW)
<ul> <li>Functionally Equivalent to 'ALS29864 and AMD Am29864A</li> </ul>	
• Power-Up High-Impedance State	A1   2 23   B1 A2   3 22   B2
<ul> <li>ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015</li> </ul>	A3 [ 4 21 ] B3 A4 [ 5 20 ] B4
Package Options Include Plastic	A5 🛛 6 19 🕽 B5
Small-Outline (DW) Packages and Standard	A6 🛛 7 18 🗋 B6
Plastic 300-mil DIPs (NT)	A7 4 8 17 B7
departmention	
description	<u>A9</u> [] 10 15 [] <u>B9</u>
This 9-bit transceiver is designed for asynchronous communication between data	OEBA2 11 14 OEAB2 GND 12 13 OEAB1

buses. The control-function implementation allows for maximum flexibility in timing.

The device allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending upon the logic levels at the output-enable (OEBA and OEAB) inputs.

The outputs are in the high-impedance state during power-up and power-down conditions. The outputs remain in the high-impedance state while the device is powered-down.

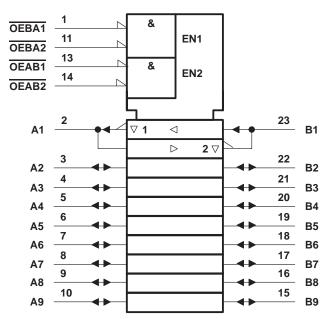
	FUNCTION TABLE								
	INP	OPERATION							
OEAB1	OEAB2	OEBA1	OEBA2	OPERATION					
L	L	L	L	Latch A and B					
L	L	Н	Х	A to B					
L	L	Х	Н	AIUB					
Н	Х	L	L	B to A					
Х	Н	L	L	B IO A					
н	Х	Н	Х						
н	Х	Х	Н	Isolation					
X	Н	Х	н	1501411011					
Х	Н	Н	Х						

The SN74BCT29864B is characterized for operation from 0°C to 70°C.

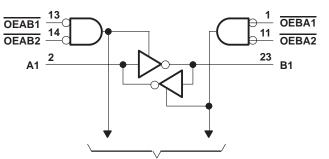
# SN74BCT29864B 9-BIT BUS TRANSCEIVER WITH 3-STATE OUTPUTS

SCBS010A - NOVEMBER 1988 - REVISED NOVEMBER 1993

#### logic symbol<sup>†</sup>



logic diagram (positive logic)



To Eight Other Channels

<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>‡</sup>

Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
 NOTE 1: The negative voltage rating may be exceeded if the input current rating is observed.

#### recommended operating conditions

		MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
VIL	Low-level input voltage			0.8	V
IIK	Input clamp current			-18	mA
IOH	High-level output current			-24	mA
IOL	Low-level output current			48	mA
TA	Operating free-air temperature	0		70	°C



# SN74BCT29864B 9-BIT BUS TRANSCEIVER WITH 3-STATE OUTPUTS

SCBS010A - NOVEMBER 1988 - REVISED NOVEMBER 1993

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER		MIN	TYP <sup>†</sup>	MAX	UNIT	
VIK		V <sub>CC</sub> = 4.5 V,	II = -18 mA			-1.2	V
			I <sub>OH</sub> = -15 mA	2.4	3.3		
∨он		VCC = 4.5 V	$V_{CC} = 4.5 V$ $I_{OH} = -24 \text{ mA}$		3.1		V
		V <sub>CC</sub> = 4.75 V,	$I_{OH} = -3 \text{ mA}$	2.7			
VOL		V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 48 mA		0.35	0.5	V
lj –		V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 5.5 V			0.1	mA
1	Control inputs					20	A
lιΗ	A or B port‡	$V_{CC} = 5.5 V,$	V <sub>I</sub> = 2.7 V			20	μA
L.	Control inputs					-0.2	
ΊL	A or B port‡	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 0.5 V			-0.2	mA
IIO(off)	)§	$V_{CC} = 0,$	V <sub>O</sub> = 2.7 V			0.1	mA
los¶		V <sub>CC</sub> = 5.5 V,	$V_{O} = 0$	-75		-250	mA
			Outputs high		18	30	
ICC	V <sub>CC</sub> = 5.5 V		Outputs low		30	45	mA
			Outputs disabled		6.5	12	
Ci		$V_{CC} = 5 V,$	$V_{I} = 0.5 V \text{ or } 2.5 V$		6		pF
Cio		V <sub>CC</sub> = 5 V,	$V_{I} = 0.5 V \text{ or } 2.5 V$		8		pF

<sup>†</sup> All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C. <sup>‡</sup> For I/O ports, the parameters I<sub>IH</sub> and I<sub>IL</sub> include the off-state output current.

§ IO(off) = Power-off bus leakage current

Not more than one output should be shorted at a time and duration of the short circuit should not exceed one second.

#### switching characteristics (see Note 2)

PARAMETER	FROM (INPUT)	то (оитрит)	CL R1 R2	c = 5 V, = 50 pF = 500 Ω = 500 Ω = 25°C	;, <u>)</u> , <u>)</u> ,	$V_{CC} = 4.5$ $C_L = 50 \text{ pl}$ R1 = 500  g R2 = 500  g $T_A = \text{MIN} \text{ f}$	2, 2,	UNIT
			MIN	TYP	MAX	MIN	MAX	
<sup>t</sup> PLH	A or B	B or A	1	3.5	5.3	1	6.1	ns
<sup>t</sup> PHL	AUD	BUIA	0.5	2.3	4.6	0.5	4.8	115
<sup>t</sup> PZH	0510 0504	A or B	2.3	5	7.2	2.3	8.4	ns
tPZL	OEAB or OEBA	AUD	4.3	7.3	10.6	4.3	12.5	115
<sup>t</sup> PHZ	OEAB or OEBA	A or B	2.3	4.6	7.6	2.3	8.4	ns
t <sub>PLZ</sub>		AUD	2	4	7	2	8.2	115

<sup>#</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74BCT29864BDW	ACTIVE	SOIC	DW	24	25	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR Level-1-235C-UNLIM
SN74BCT29864BDWR	ACTIVE	SOIC	DW	24	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR Level-1-235C-UNLIM
SN74BCT29864BNT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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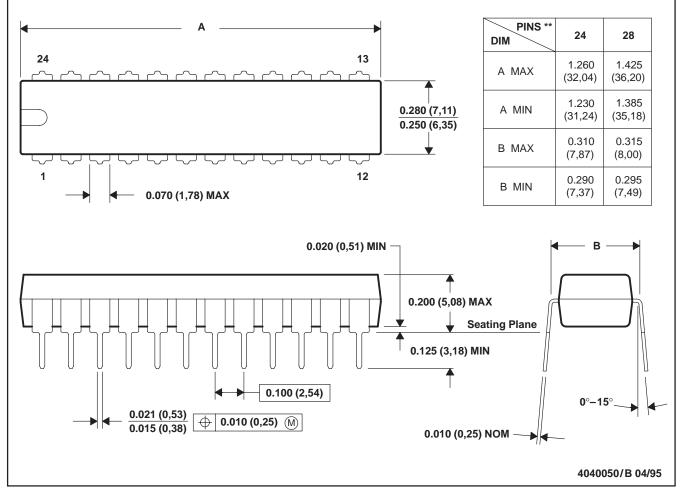
# **MECHANICAL DATA**

MPDI004 - OCTOBER 1994

#### NT (R-PDIP-T\*\*)

#### PLASTIC DUAL-IN-LINE PACKAGE

24 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters). B. This drawing is subject to change without notice.



DW (R-PDSO-G24)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AD.



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Mailing Address:

Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

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